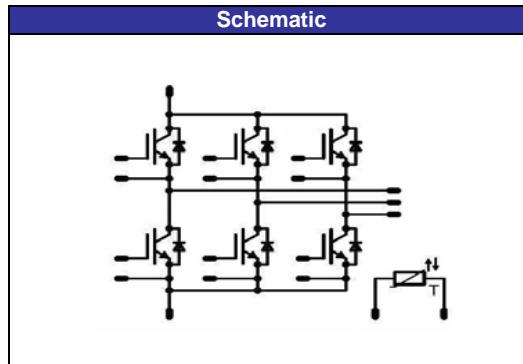


flow90PACK 1 2nd gen
1200V/8A

Features
• Trench Fieldstop IGBT4 Technology
• Supports designs with 90° mounting angle between heatsink and PCB
• Clip-in PCB mounting
• Clip or screw hetasink mounting



Target Applications
• Motor Drives



Types
• V23990-P707-F40-PM

Maximum Ratings
 $T_j=25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

Inverter IGBT

Collector-emitter break down voltage	V_{CE}		1200	V
DC collector current	I_C	$T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$	14 17	A
Repetitive peak collector current	I_{Cpulse}	t_p limited by $T_{j\max}$	24	A
Turn off safe operating area		$V_{CE} \leq 1200\text{V}$, $T_j \leq T_{j\max}$	24	A
Power dissipation per IGBT	P_{tot}	$T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$	50 76	W
Gate-emitter peak voltage	V_{GE}		± 20	V
Short circuit ratings	t_{SC} V_{CC}	$T_j \leq 150^\circ\text{C}$ $V_{GE}=15\text{V}$	10 800	μs V
Maximum Junction Temperature	$T_{j\max}$		175	$^\circ\text{C}$

Inverter FWD

Peak Repetitive Reverse Voltage	V_{RRM}	$T_j=25^\circ\text{C}$	1200	V
DC forward current	I_F	$T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$	13 16	A
Repetitive peak forward current	I_{FRM}	t_p limited by $T_{j\max}$	20	A
Power dissipation per Diode	P_{tot}	$T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$	40 61	W
Maximum Junction Temperature	$T_{j\max}$		175	$^\circ\text{C}$

Maximum Ratings

$T_j=25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{op}		-40...+($T_{jmax} - 25$)	°C

Insulation Properties

Insulation voltage	V_{is}	t=2s	DC voltage	4000	V
Creepage distance				min 12,7	mm
Clearance				min 12,7	mm
Comparative tracking index	CTI			>200	

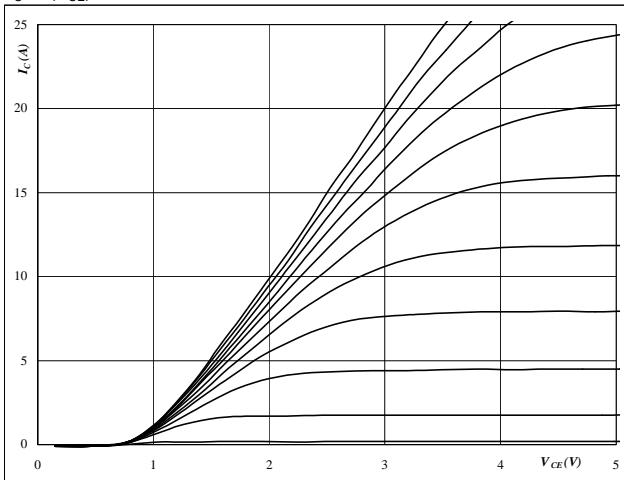
Characteristic Values

Parameter	Symbol	Conditions				Value			Unit	
			V_{GE} [V] or V_{GS} [V]	V_r [V] or V_{CE} [V] or V_{DS} [V]	I_c [A] or I_F [A] or I_D [A]	T_j	Min	Typ	Max	
Inverter IGBT										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$			0,0003	$T_j=25^\circ C$ $T_j=150^\circ C$	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		8	$T_j=25^\circ C$ $T_j=150^\circ C$	1,3	1,88 2,16	2,3	V
Collector-emitter cut-off current incl. Diode	I_{CES}		0	1200		$T_j=25^\circ C$ $T_j=150^\circ C$			0,001	mA
Gate-emitter leakage current	I_{GES}		20	0		$T_j=25^\circ C$ $T_j=150^\circ C$			120	nA
Integrated Gate resistor	R_{gint}							none		Ω
Turn-on delay time	$t_{d(on)}$	$R_{goff}=64 \Omega$ $R_{gon}=64 \Omega$	± 15	600	8	$T_j=25^\circ C$ $T_j=150^\circ C$	106 104			ns
Rise time	t_r					$T_j=25^\circ C$ $T_j=150^\circ C$	25 28			
Turn-off delay time	$t_{d(off)}$					$T_j=25^\circ C$ $T_j=150^\circ C$	227 297			
Fall time	t_f					$T_j=25^\circ C$ $T_j=150^\circ C$	68 140			
Turn-on energy loss per pulse	E_{on}					$T_j=25^\circ C$ $T_j=150^\circ C$	0,66 1,01			mWs
Turn-off energy loss per pulse	E_{off}					$T_j=25^\circ C$ $T_j=150^\circ C$	0,48 0,81			
Input capacitance	C_{ies}	$f=1MHz$	0	25		$T_j=25^\circ C$	490			pF
Output capacitance	C_{oss}						50			
Reverse transfer capacitance	C_{rss}						30			
Gate charge	Q_{Gate}		± 15	960	8	$T_j=25^\circ C$	45			nC
Thermal resistance chip to heatsink per chip	R_{thJH}	Thermal grease thickness≤50um $\lambda = 1 W/mK$						1,90		K/W
Inverter FWD										
Diode forward voltage	V_F				10	$T_j=25^\circ C$ $T_j=150^\circ C$	1	1,77 1,69	2,2	V
Peak reverse recovery current	I_{RRM}	$R_{gon}=64 \Omega$	± 15	600	8	$T_j=25^\circ C$ $T_j=150^\circ C$	8 9			A
Reverse recovery time	t_{rr}					$T_j=25^\circ C$ $T_j=150^\circ C$	271 448			ns
Reverse recovered charge	Q_{rr}					$T_j=25^\circ C$ $T_j=150^\circ C$	0,84 1,72			μC
Peak rate of fall of recovery current	$di(rec)max/dt$					$T_j=25^\circ C$ $T_j=150^\circ C$	29 24			$A/\mu s$
Reverse recovered energy	E_{rec}					$T_j=25^\circ C$ $T_j=150^\circ C$	0,30 0,64			mWs
Thermal resistance chip to heatsink per chip	R_{thJH}	Thermal grease thickness≤50um $\lambda = 1 W/mK$						2,36		K/W
Thermistor										
Rated resistance	R					$T_j=25^\circ C$		22000		Ω
Deviation of R100	$\Delta R/R$	$R_{100}=1486 \Omega$				$T_c=100^\circ C$	-5		5	%
Power dissipation	P					$T_c=100^\circ C$		200		mW
Power dissipation constant						$T_j=25^\circ C$		2		mW/K
B-value	$B_{(25/50)}$	Tol. ±3%				$T_j=25^\circ C$		3950		K
B-value	$B_{(25/100)}$	Tol. ±3%				$T_j=25^\circ C$		3996		K
Vincotech NTC Reference						$T_j=25^\circ C$			B	

Output Inverter

Figure 1**Typical output characteristics**

$$I_C = f(V_{CE})$$

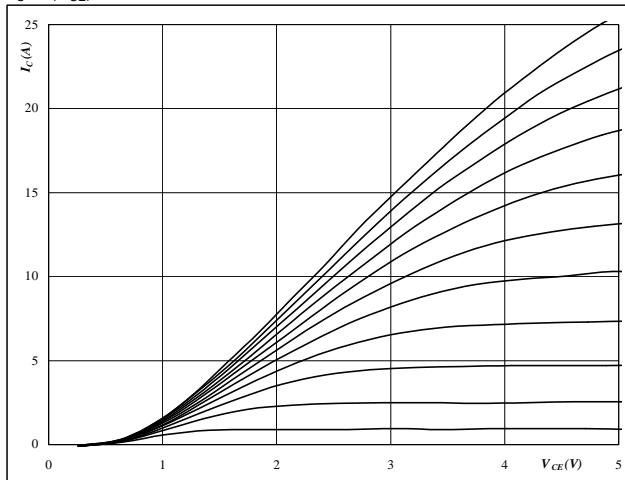
**At**

$$t_p = 250 \mu\text{s}$$

$$T_j = 25^\circ\text{C}$$

 V_{GE} from 7 V to 17 V in steps of 1 V
Figure 2**Typical output characteristics**

$$I_C = f(V_{CE})$$

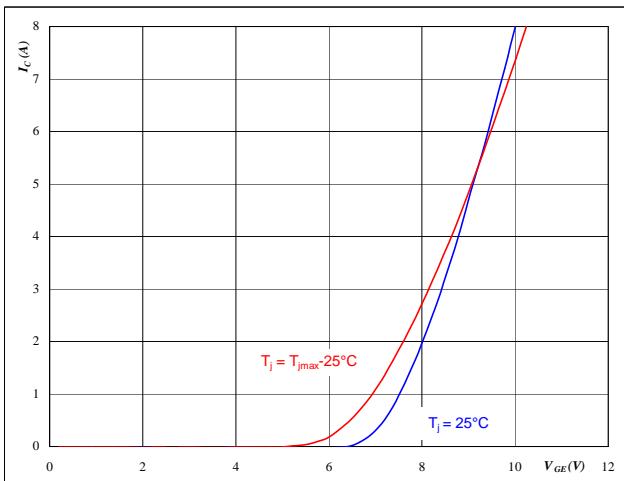
**At**

$$t_p = 250 \mu\text{s}$$

$$T_j = 150^\circ\text{C}$$

 V_{GE} from 7 V to 17 V in steps of 1 V
Figure 3**Typical transfer characteristics**

$$I_C = f(V_{GE})$$

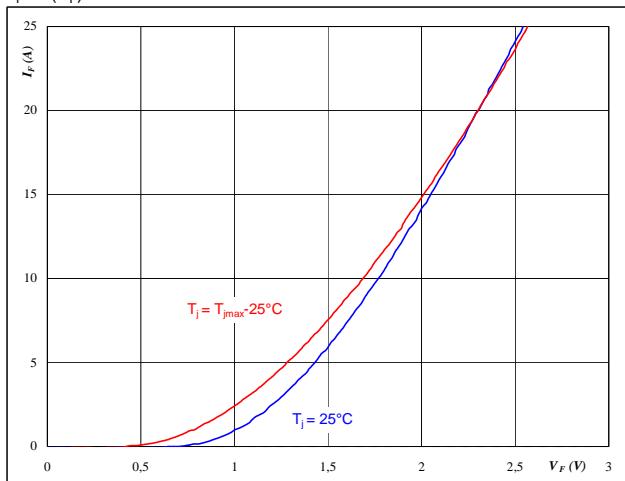
**At**

$$t_p = 250 \mu\text{s}$$

$$V_{CE} = 10 \text{ V}$$

Figure 4**Typical diode forward current as a function of forward voltage**

$$I_F = f(V_F)$$

**At**

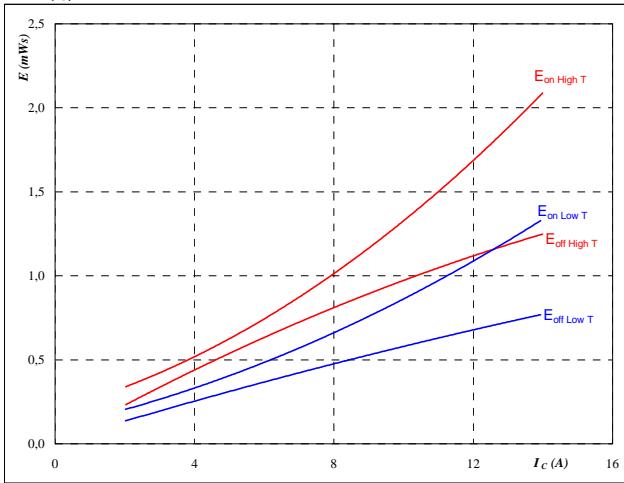
$$t_p = 250 \mu\text{s}$$

Output Inverter

Figure 5

**Typical switching energy losses
as a function of collector current**

$$E = f(I_C)$$



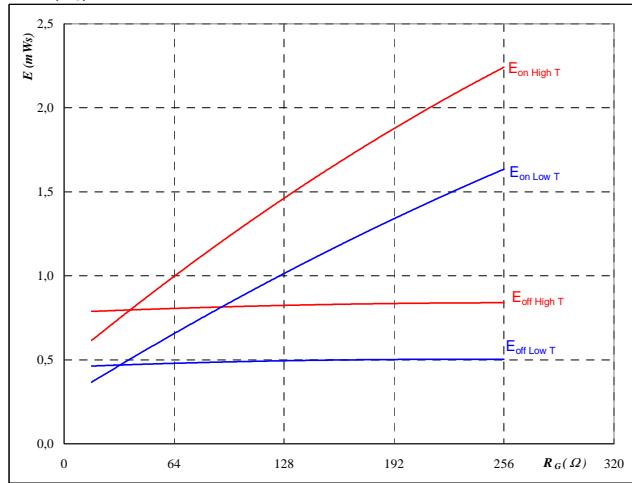
With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 64 \quad \Omega \\ R_{goff} &= 64 \quad \Omega \end{aligned}$$

Output inverter IGBT
Figure 6

**Typical switching energy losses
as a function of gate resistor**

$$E = f(R_G)$$



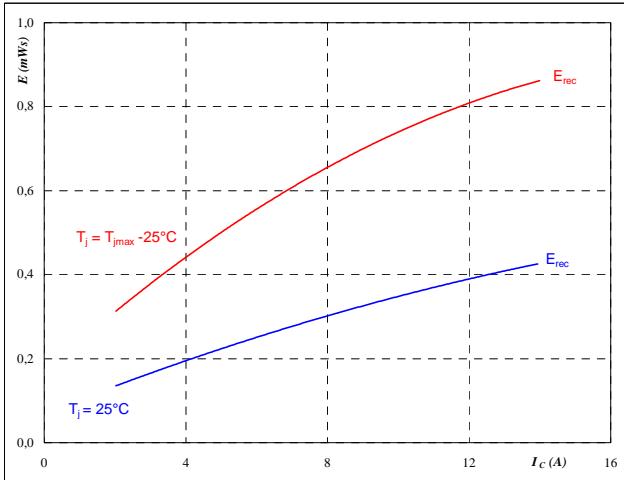
With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ I_C &= 8 \quad \text{A} \\ R_{gon} &= 64 \quad \Omega \\ R_{goff} &= 64 \quad \Omega \end{aligned}$$

Figure 7
Output inverter FWD

**Typical reverse recovery energy loss
as a function of collector current**

$$E_{rec} = f(I_C)$$



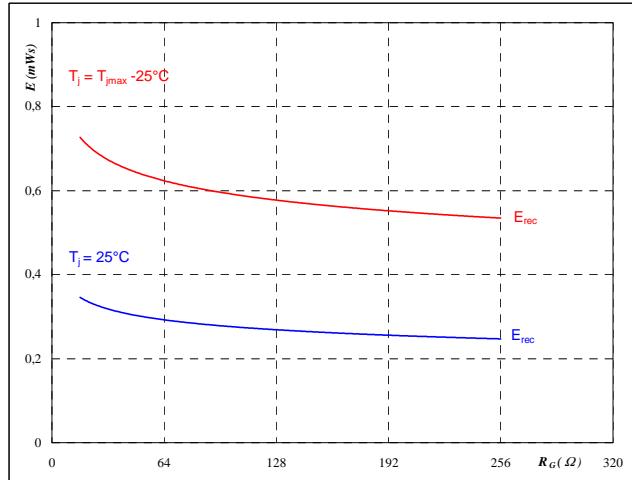
With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 64 \quad \Omega \end{aligned}$$

Figure 8
Output inverter FWD

**Typical reverse recovery energy loss
as a function of gate resistor**

$$E_{rec} = f(R_G)$$



With an inductive load at

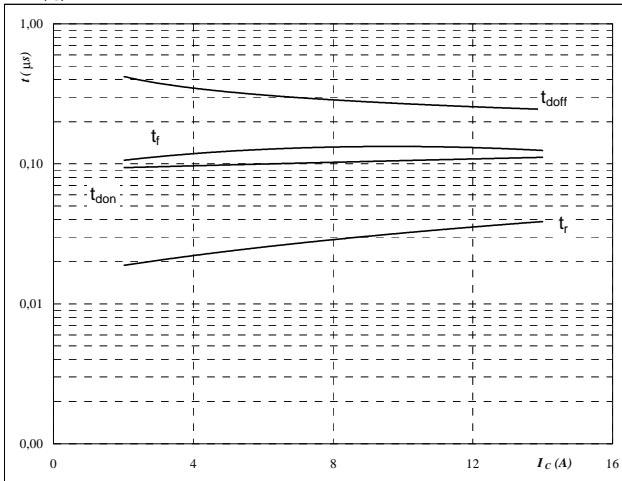
$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ I_C &= 8 \quad \text{A} \\ R_{gon} &= 64 \quad \Omega \\ R_{goff} &= 64 \quad \Omega \end{aligned}$$

Output Inverter

Figure 9

Typical switching times as a function of collector current

$$t = f(I_C)$$



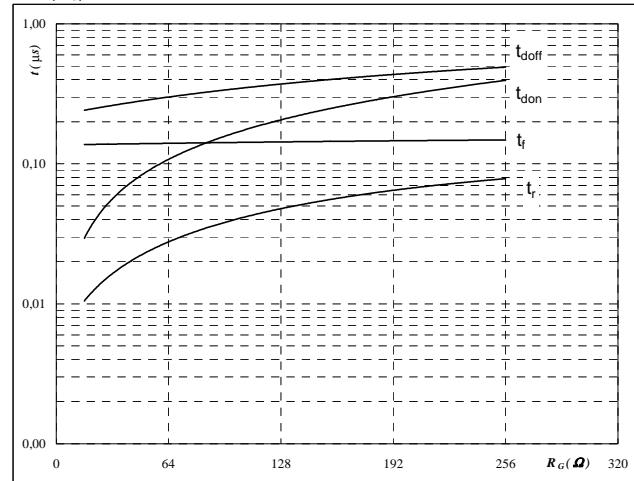
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω
$R_{goff} =$	64	Ω

Figure 10

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



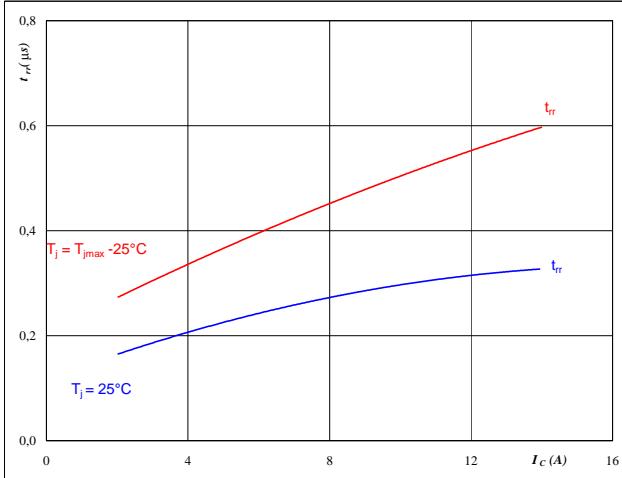
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	8	A

Figure 11
Output inverter FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$



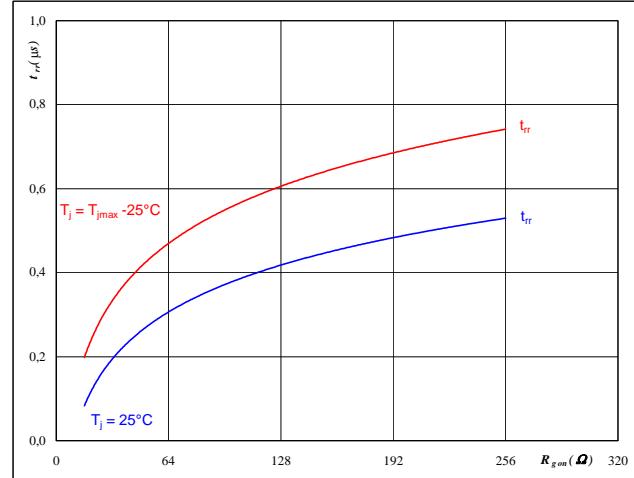
At

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω

Figure 12
Output inverter FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At

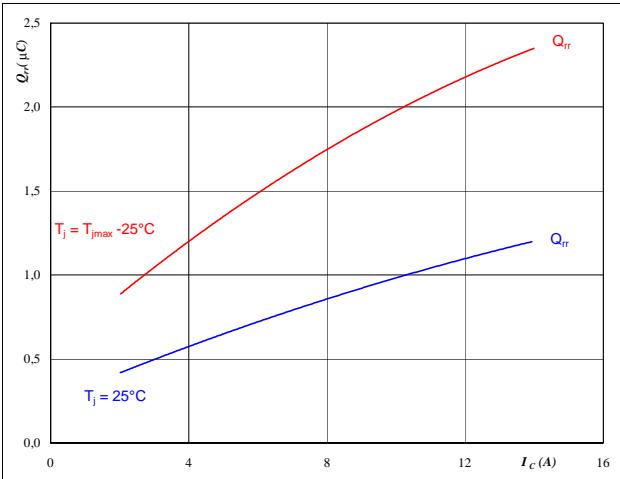
$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	8	A
$V_{GE} =$	±15	V

Output Inverter

Figure 13

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$

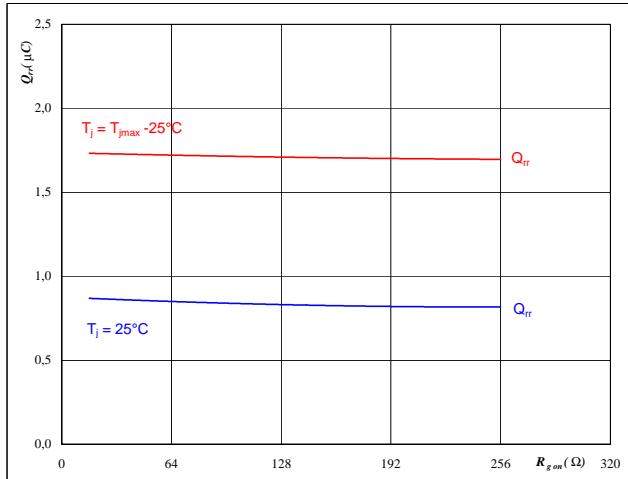
**At**

$$\begin{aligned} T_j &= 25/150 \quad {}^\circ C \\ V_{CE} &= 600 \quad V \\ V_{GE} &= \pm 15 \quad V \\ R_{gon} &= 64 \quad \Omega \end{aligned}$$

Output inverter FWD**Figure 14**

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$

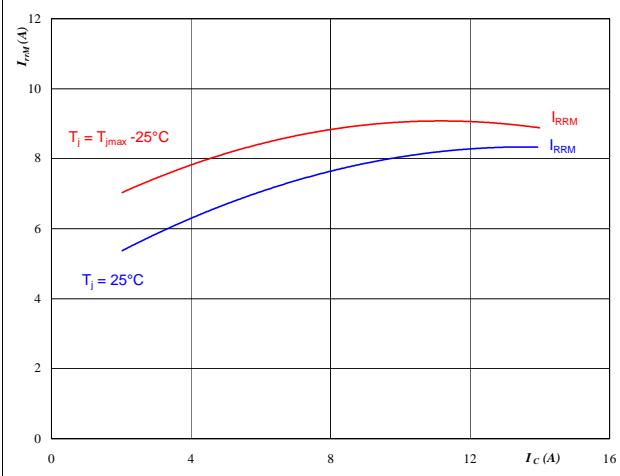
**At**

$$\begin{aligned} T_j &= 25/150 \quad {}^\circ C \\ V_R &= 600 \quad V \\ I_F &= 8 \quad A \\ V_{GE} &= \pm 15 \quad V \end{aligned}$$

Figure 15**Output inverter FWD**

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$

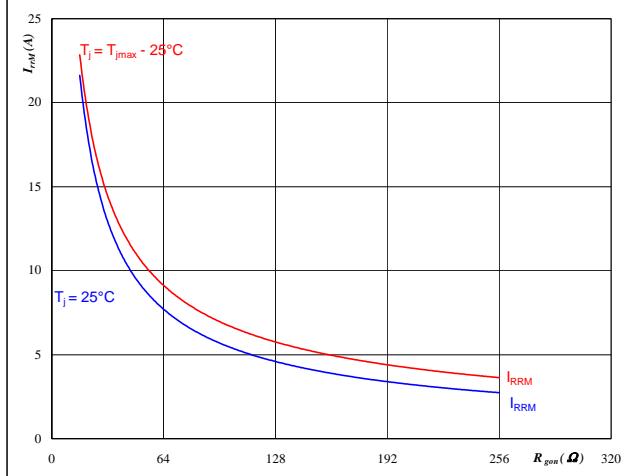
**At**

$$\begin{aligned} T_j &= 25/150 \quad {}^\circ C \\ V_{CE} &= 600 \quad V \\ V_{GE} &= \pm 15 \quad V \\ R_{gon} &= 64 \quad \Omega \end{aligned}$$

Figure 16**Output inverter FWD**

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$

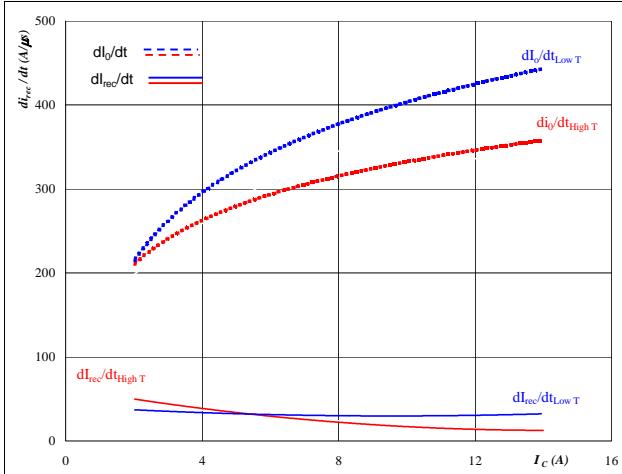
**At**

$$\begin{aligned} T_j &= 25/150 \quad {}^\circ C \\ V_R &= 600 \quad V \\ I_F &= 8 \quad A \\ V_{GE} &= \pm 15 \quad V \end{aligned}$$

Output Inverter

Figure 17

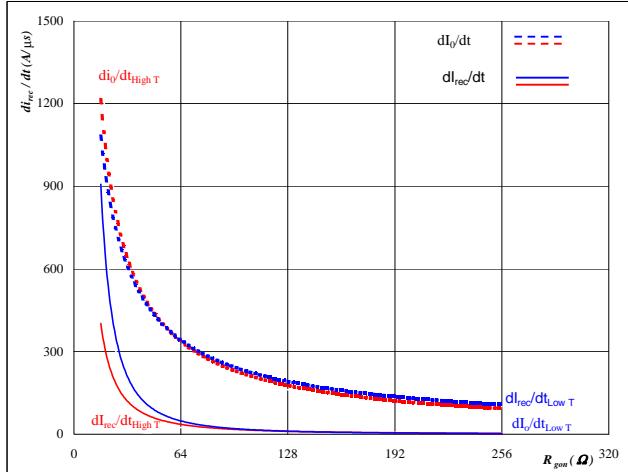
Typical rate of fall of forward
and reverse recovery current as a
function of collector current
 $dI_0/dt, dI_{rec}/dt = f(I_C)$

**At**

$T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 64 \Omega$

Output inverter FWD
Figure 18

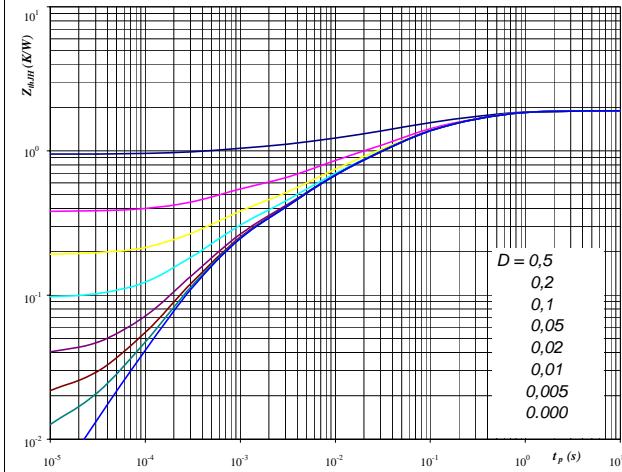
Typical rate of fall of forward
and reverse recovery current as a
function of IGBT turn on gate resistor
 $dI_0/dt, dI_{rec}/dt = f(R_{gon})$

**At**

$T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_R = 600 \text{ V}$
 $I_F = 8 \text{ A}$
 $V_{GE} = \pm 15 \text{ V}$

Figure 19

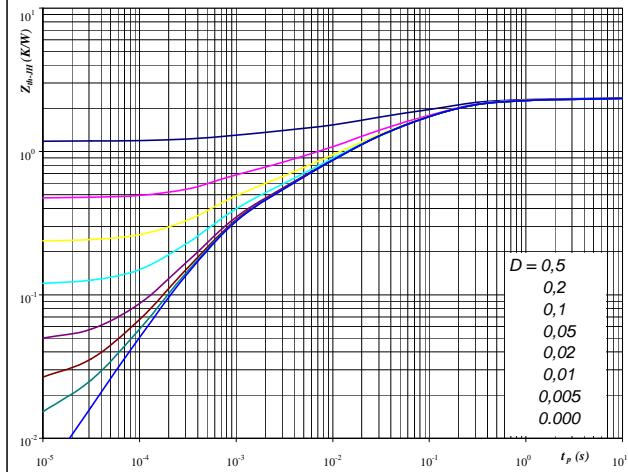
IGBT transient thermal impedance
as a function of pulse width
 $Z_{thJH} = f(t_p)$

**At**

$D = t_p / T$
 $R_{thJH} = 1.90 \text{ K/W}$

Output inverter IGBT
Figure 20

FWD transient thermal impedance
as a function of pulse width
 $Z_{thJH} = f(t_p)$

**At**

$D = t_p / T$
 $R_{thJH} = 2.36 \text{ K/W}$

IGBT thermal model values

Thermal grease		Phase change interface	
R (C/W)	Tau (s)	R (C/W)	Tau (s)
0,08	1,6E+00	0,06	1,3E+00
0,54	2,7E-01	0,44	2,2E-01
0,67	4,7E-02	0,54	3,8E-02
0,41	6,5E-03	0,34	5,3E-03
0,21	5,7E-04	0,17	4,6E-04

FWD thermal model values

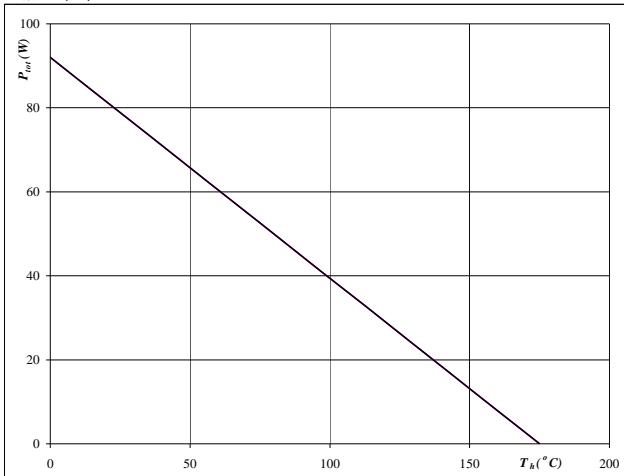
Thermal grease		Phase change interface	
R (C/W)	Tau (s)	R (C/W)	Tau (s)
0,07	5,6E+00	0,06	4,5E+00
0,25	4,7E-01	0,20	3,8E-01
1,04	8,9E-02	0,84	7,2E-02
0,65	1,0E-02	0,53	8,2E-03
0,34	7,5E-04	0,28	6,1E-04

Output Inverter

Figure 21

Power dissipation as a function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

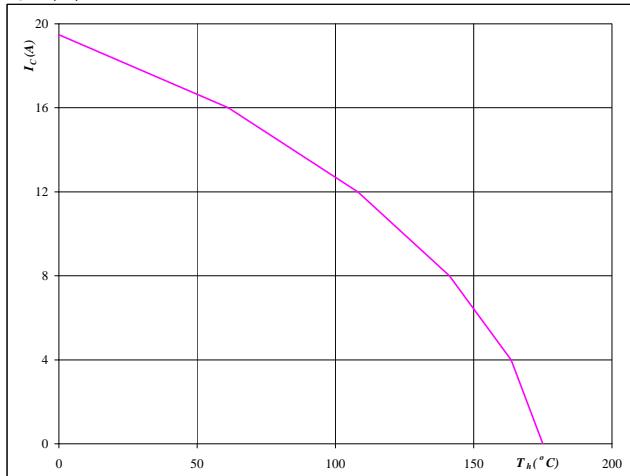
**At**

$$T_j = 175 \quad ^\circ\text{C}$$

Output inverter IGBT**Figure 22**

Collector current as a function of heatsink temperature

$$I_C = f(T_h)$$

**At**

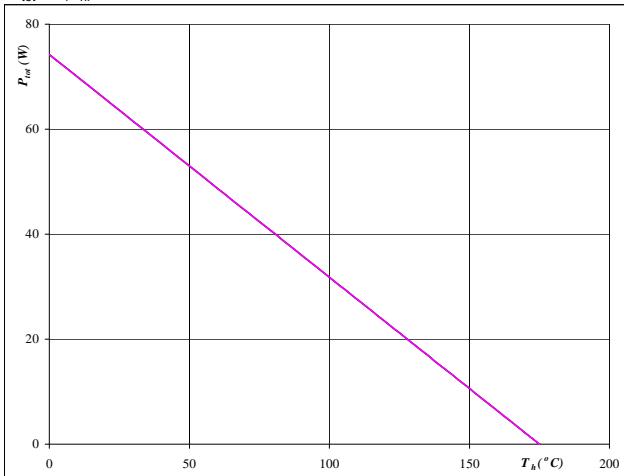
$$T_j = 175 \quad ^\circ\text{C}$$

$$V_{GE} = 15 \quad \text{V}$$

Figure 23**Output inverter FWD**

Power dissipation as a function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

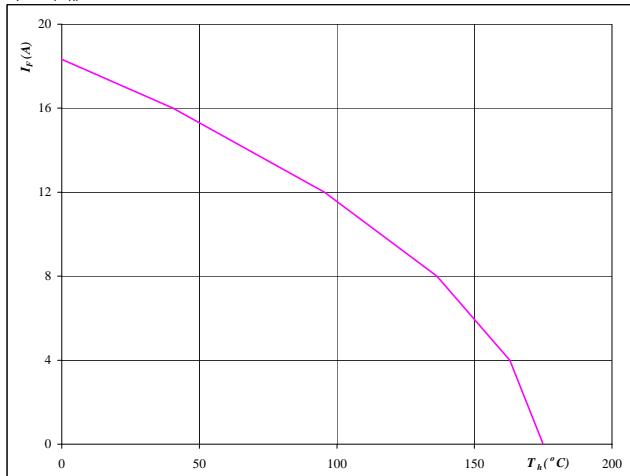
**At**

$$T_j = 175 \quad ^\circ\text{C}$$

Figure 24**Output inverter FWD**

Forward current as a function of heatsink temperature

$$I_F = f(T_h)$$

**At**

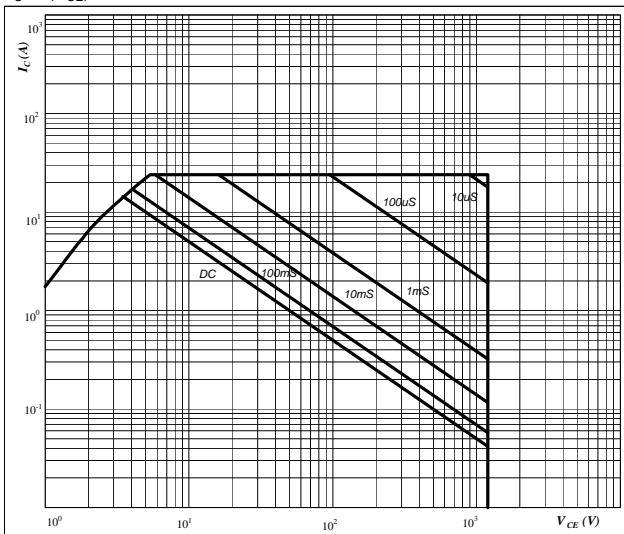
$$T_j = 175 \quad ^\circ\text{C}$$

Output Inverter

Figure 25

Safe operating area as a function of collector-emitter voltage

$$I_C = f(V_{CE})$$


At

D = single pulse

T_h = 80 °C

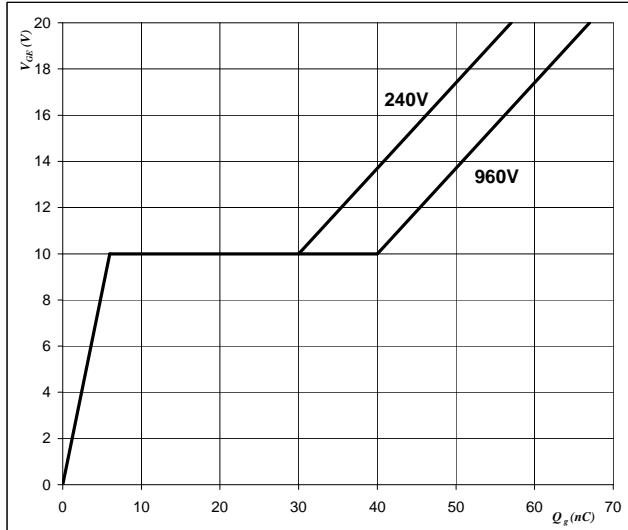
V_{GE} = ±15 V

T_j = T_{jmax} °C

Output inverter IGBT
Figure 26

Gate voltage vs Gate charge

$$V_{GE} = f(Q_{GE})$$

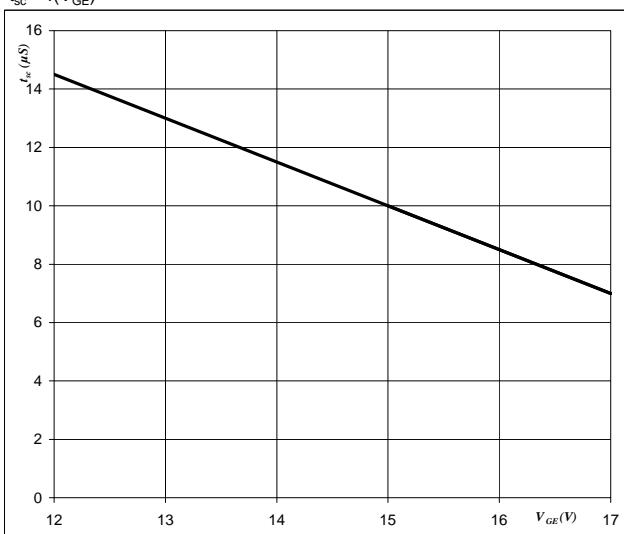

At

I_C = 8 A

Figure 27
Output inverter IGBT

Short circuit withstand time as a function of gate-emitter voltage

$$t_{sc} = f(V_{GE})$$


At

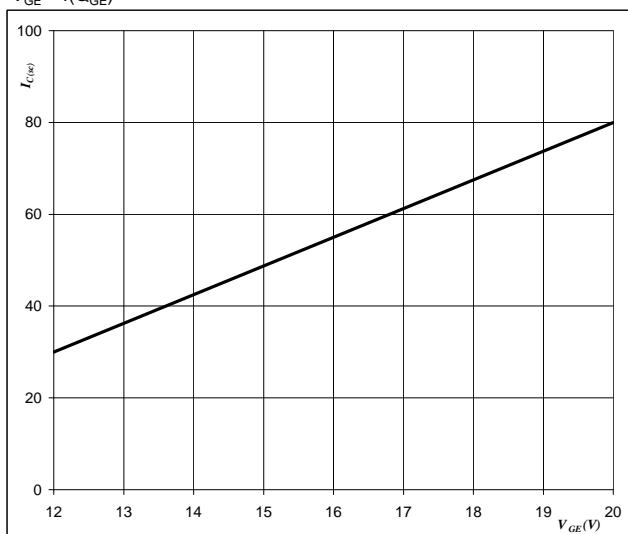
V_{CE} = 1200 V

T_j ≤ 175 °C

Figure 28
Output inverter IGBT

Typical short circuit collector current as a function of gate-emitter voltage

$$I_{C(sc)} = f(V_{GE})$$

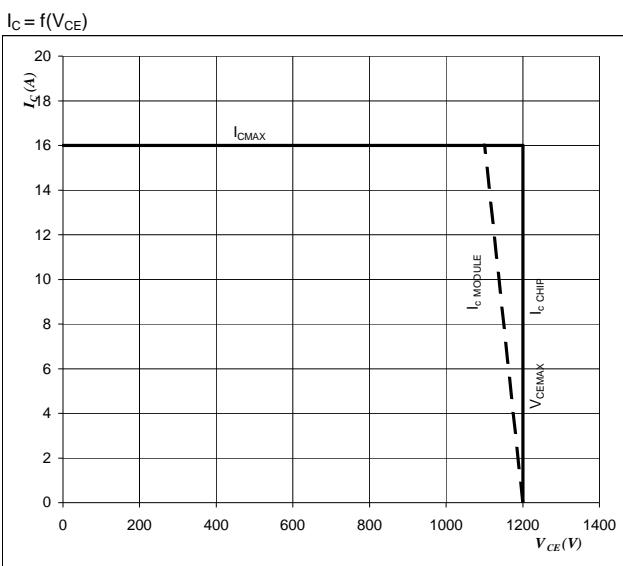

At

V_{CE} ≤ 1200 V

T_j = 175 °C

Figure 29

IGBT

Reverse bias safe operating area**At** $T_j = T_{j\text{max}} - 25 \quad ^\circ\text{C}$ $U_{ccminus} = U_{ccplus}$

Switching mode : 3phase SPWM

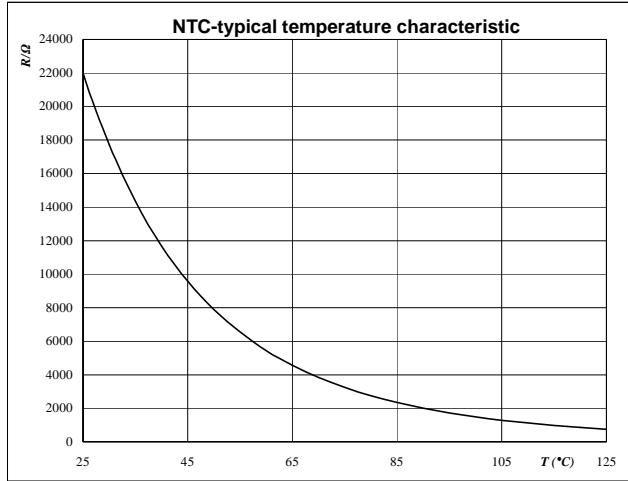
Thermistor

Figure 1

**Typical NTC characteristic
as a function of temperature**

$$R_T = f(T)$$

Thermistor

**Figure 2**

Typical NTC resistance values

Thermistor

$$R(T) = R_{25} \cdot e^{\left(B_{25/100} \left(\frac{1}{T} - \frac{1}{T_{25}} \right) \right)} \quad [\Omega]$$

Switching Definitions Output Inverter

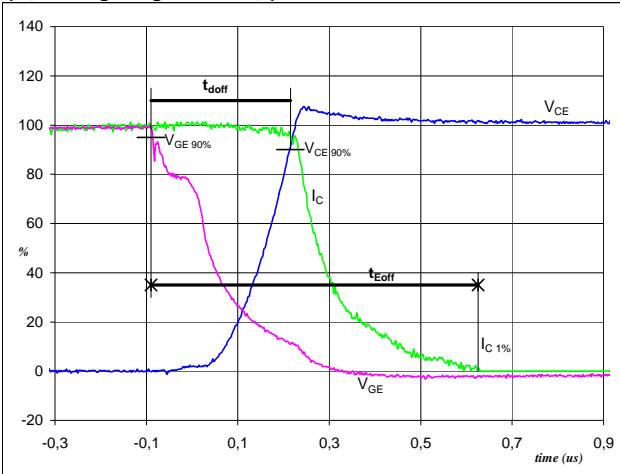
General conditions

T_j	=	150 °C
R_{gon}	=	64 Ω
R_{goff}	=	64 Ω

Figure 1

Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
 $(t_{Eoff} = \text{integrating time for } E_{off})$

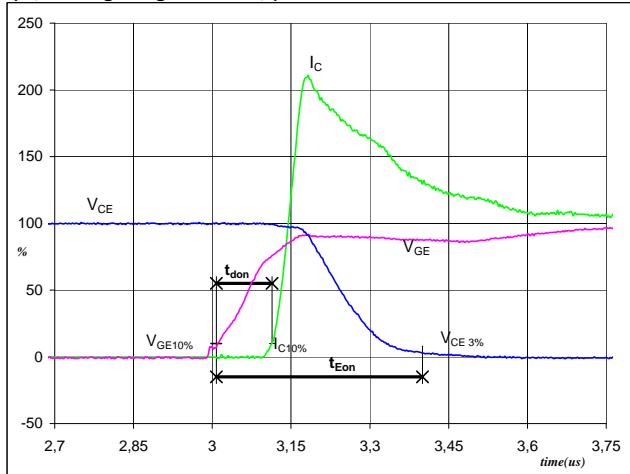


$V_{GE}(0\%) = -15$ V
 $V_{GE}(100\%) = 15$ V
 $V_C(100\%) = 600$ V
 $I_C(100\%) = 8$ A
 $t_{doff} = 0,30$ μs
 $t_{Eoff} = 0,72$ μs

Figure 2

Output inverter IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}
 $(t_{Eon} = \text{integrating time for } E_{on})$

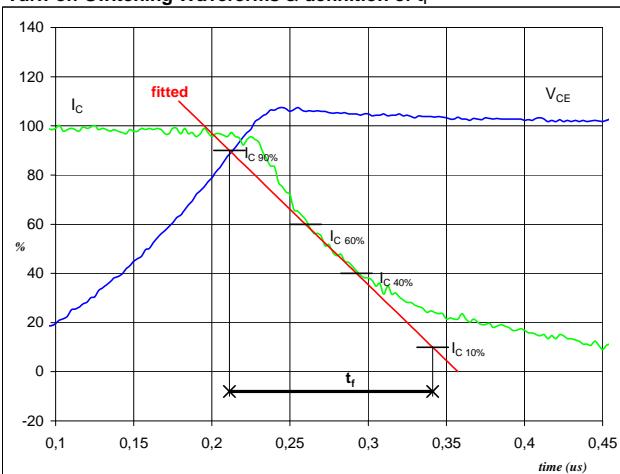


$V_{GE}(0\%) = -15$ V
 $V_{GE}(100\%) = 15$ V
 $V_C(100\%) = 600$ V
 $I_C(100\%) = 8$ A
 $t_{don} = 0,10$ μs
 $t_{Eon} = 0,39$ μs

Figure 3

Output inverter IGBT

Turn-off Switching Waveforms & definition of t_f

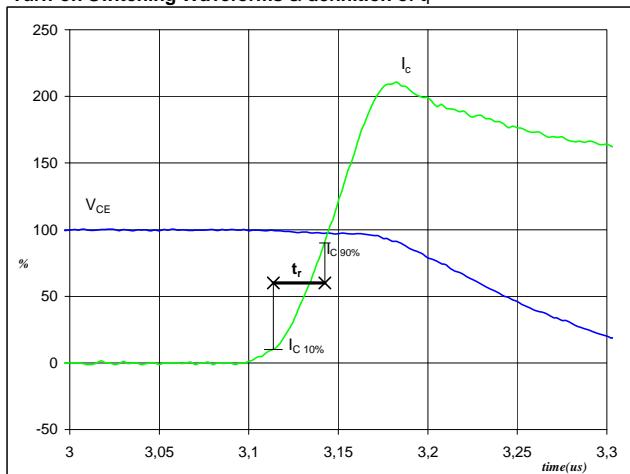


$V_C(100\%) = 600$ V
 $I_C(100\%) = 8$ A
 $t_f = 0,14$ μs

Figure 4

Output inverter IGBT

Turn-on Switching Waveforms & definition of t_r

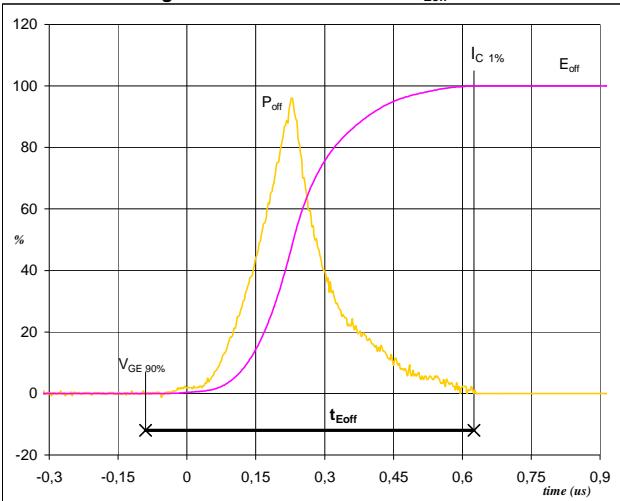


$V_C(100\%) = 600$ V
 $I_C(100\%) = 8$ A
 $t_r = 0,03$ μs

Switching Definitions Output Inverter

Figure 5

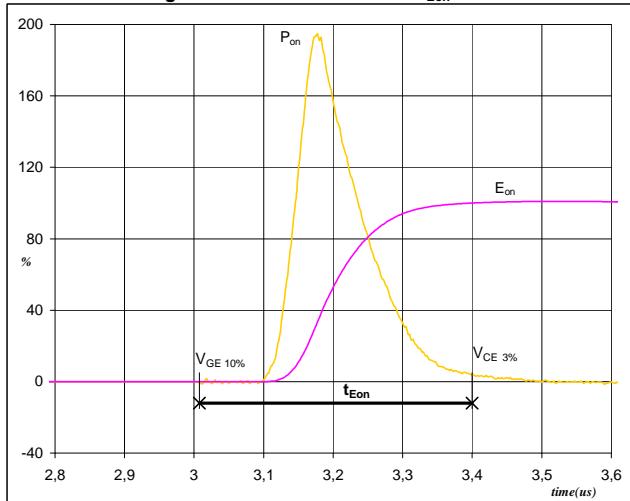
Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{Eoff} 

P_{off} (100%) = 4,78 kW
 E_{off} (100%) = 0,81 mJ
 t_{Eoff} = 0,72 μ s

Figure 6

Output inverter IGBT

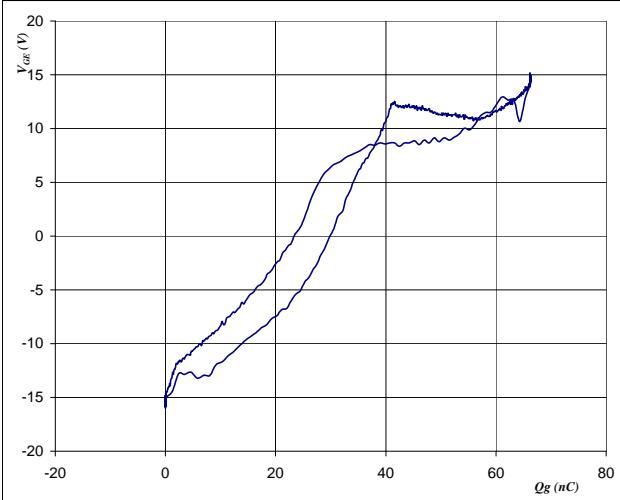
Turn-on Switching Waveforms & definition of t_{Eon} 

P_{on} (100%) = 4,78 kW
 E_{on} (100%) = 1,01 mJ
 t_{Eon} = 0,39 μ s

Figure 7

Output inverter FWD

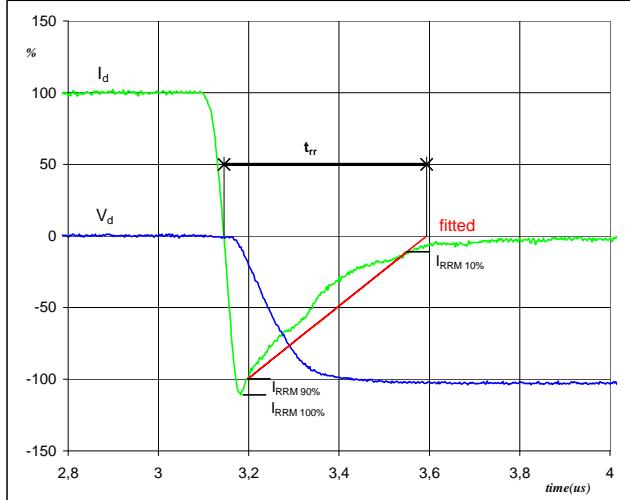
Gate voltage vs Gate charge (measured)



V_{GEoff} = -15 V
 V_{GEon} = 15 V
 V_C (100%) = 600 V
 I_C (100%) = 8 A
 Q_g = 66,35 nC

Figure 8

Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{rr} 

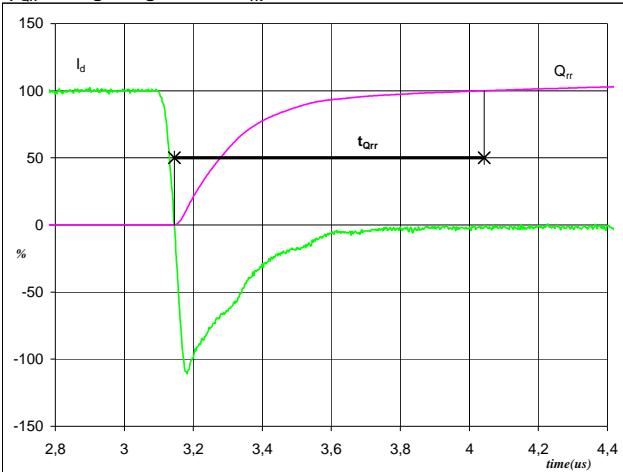
V_d (100%) = 600 V
 I_d (100%) = 8 A
 I_{RRM} (100%) = -9 A
 t_{rr} = 0,45 μ s

Switching Definitions Output Inverter

Figure 9

Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Qrr}
 $(t_{Qrr} = \text{integrating time for } Q_{rr})$

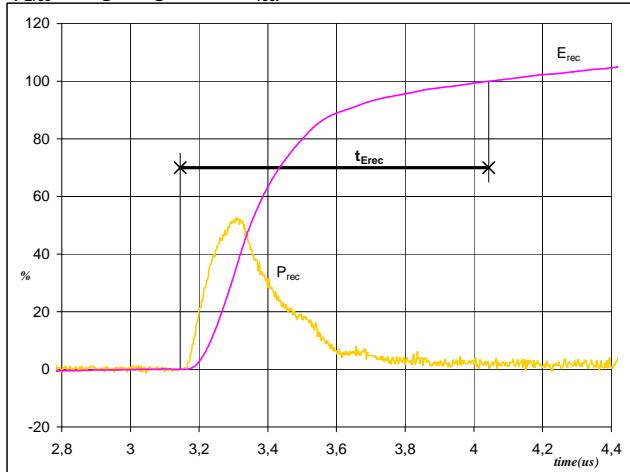


$$\begin{aligned} I_d(100\%) &= 8 \quad \text{A} \\ Q_{rr}(100\%) &= 1,72 \quad \mu\text{C} \\ t_{Qrr} &= 0,90 \quad \mu\text{s} \end{aligned}$$

Figure 10

Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Erec}
 $(t_{Erec} = \text{integrating time for } E_{rec})$



$$\begin{aligned} P_{rec}(100\%) &= 4,78 \quad \text{kW} \\ E_{rec}(100\%) &= 0,64 \quad \text{mJ} \\ t_{Erec} &= 0,90 \quad \mu\text{s} \end{aligned}$$

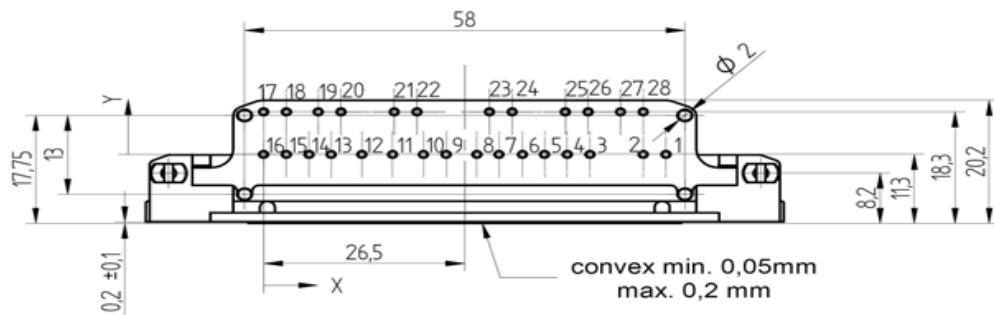
Ordering Code and Marking - Outline - Pinout

Ordering Code & Marking

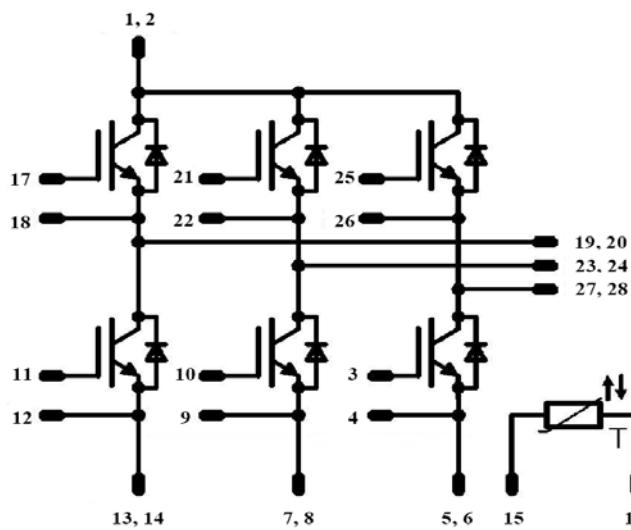
Version	Ordering Code	in DataMatrix as	in packaging barcode as
without thermal paste 12mm housing	V23990-P707-F40	P707-F40	P707-F40

Outline

Pin Table		
Pin	X	Y
1	53	0
2	50	0
3	43	0
4	40	0
5	37	0
6	34,1	0
7	31	0
8	28,1	0
9	24,05	0
10	21,05	0
11	17	0
12	12,95	0
13	8,9	0
14	6	0
15	3	0
16	0	0
17	0	7
18	3	7
19	7,2	7
20	10,2	7
21	17,2	7
22	20,2	7
23	29,75	7
24	32,75	7
25	39,75	7
26	42,75	7
Pin Table		
Pin	X	Y
27	47	7
28	50	7



Pinout



PRODUCT STATUS DEFINITIONS

Datasheet Status	Product Status	Definition
Target	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. The data contained is exclusively intended for technically trained staff.
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